antenna solutions


SGP.18c

## Specification

| Part No. | SGP.1575.18.4.C.02 |
| :--- | :--- |
| Product Name | GPS SMT Patch Antenna |
| Feature | 18mm*18mm*4.5mm <br> $1575 \mathrm{MHz}^{\text {Centre Frequency }}$ <br> Patent Pending <br> RoHS Compliant |

## 1. Introduction

This ceramic GPS patch antenna is based on smart XtremeGain ${ }^{\text {TM }}$ technology. It is mounted via SMT process and has been selected as optimal solution for the $45 \times 45 \mathrm{~mm}$ ground plane.

## 2. Specification

Original Patch Specification tested on 45 mm ground plane

| NO | PARAMETER | SPECIFICATION | NOTES |
| :---: | :---: | :---: | :---: |
| 1 | Range of Receiving Frequency | $1575.42 \mathrm{MHz} \pm 1.023 \mathrm{MHZ}$ |  |
| 2 | Center Frequency | $1575.42 \pm 3 \mathrm{MHz}$ | With 45*45mm Ground Plane |
| 3 | Bandwidth | 5 MHz min | Return Loss $\leq-10 \mathrm{~dB}$ |
| 4 | VSWR | 1.5 max |  |
| 5 | Gain at Zenith | +1.0 dBic typ. |  |
| 6 | Gain at $10^{\circ}$ elevation | -3.0 dBic typ. |  |
| 7 | Axial Ratio | 4.0 dB max |  |
| 8 | Polarization | RHCP |  |
| 9 | Impedance | 50 Ohms |  |
| 10 | Frequency Temperature Coefficient (Tf) | $0 \pm 20 \mathrm{ppm} /{ }^{\circ} \mathrm{C}$ | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ |
| 11 | Operating Temperature | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ |  |

**Changes in user groundplane and environment will offset centre frequency

## 3. Electrical Specifications

### 3.1 Return Loss, SWR, Impedance, measured on the test fixture



## 4. Mechanical Specifications

### 4.1 Antenna Dimensions and Drawing



NOTE:

1. Solder mask. DDD
2. Area to be soldered. DI/i/'d
3. Dimension of 50 Ohm CPW dependent

|  | Name | Part No. | Material | Finish | Quantity |
| :--- | :--- | :--- | :--- | :--- | :--- |
| 1 | SGP.18 Patch $18 \times 18 \times 4$ | SGP.18c | Ceramic | Clear | 1 |
| 2 | SGP.18 PCB |  | FR 0.5t | Green | 1 | on individual board.

4. Matching circuit-capacitor and inductor values dependent on individual environment
5. Must be soldered to complete antenna feed connection

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### 4.2 Antenna Footprint

### 4.2.1 Top Copper



Copper Keepout Region
Pads 2, 3, 4, 5, 6, 7, 8 are the same size and should be connected to 6ND. Pad 9 is a 1.70 mm dia. non-plated thru-hole.
Connect 50 ohm iransmission line to Pad 1. Copper Keepout Region should extend at least 2 mm down into PCB.

### 4.2.2 Top Paste

Dimensions in mm


### 4.2.3 Top Paste


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### 4.2.4 Composite



## Copper Keepout Region

Pads 2, 3, 4, 5, 6, 7, 8 are the same size and should be connected to GND.
Pad 9 is a 1.70 mm dia. non-plated thru-hole.
Connect 50 ohm transmission line to Pad 1.
Copper Keepout Region should extend at least 2 mm doun into PCB.

### 4.3 Test Jig and Dimension



NOTE:

1. Solder Mask (Black) $Z / 7 /$
2. Solder Area mmw

|  | Name | P/N | Material | Finish | Qty |
| :--- | :--- | :--- | :--- | :--- | :--- |
| 1 | SGP.18 Patch $18 \times 18 \times 4$ | SGP.18c | Ceramic | Clear | 1 |
| 2 | FR4 PCB |  | FR4 1t | Black | 1 |
| 3 | SMA(F)Straight Edge Mount | SMA.F.ST.JACK.PANELM.2H.CM | Brass | Gold | 1 |

### 4.4 Test Fixture set up and measurements



## 5. Recommended Reflow Soldering Profile

SGP.18.C can be assembled following Pb-free assembly. According to the Standard IPC/JEDEC J-STD020C, the temperature profile suggested is as follow:

| PHASE | PROFILE FEATURES | Pb-Free Assembly (SnAgCu) |
| :--- | :--- | :--- |
| PREHEAT | Temperature Min(Tsmin) | $150^{\circ} \mathrm{C}$ |
|  | Temperature Max(Tsmax) | $200^{\circ} \mathrm{C}$ |
|  | Timelts) from (Tsmin to Tsmax) | $60-120$ seconds |
| RAMP-UP | Avg. Ramp-up Rate (Tsmax to TP) | $3^{\circ} \mathrm{C} /$ second(max) |
| REFLOW | Temperature(TL) | $217^{\circ} \mathrm{C}$ |
| PEAK | Total Time above TL (tL) | $30-100$ seconds |
|  | Temperature(TP) | $260^{\circ} \mathrm{C}$ |
| RAMP-DOWN | Timeltp) | $2-5$ seconds |
| Time from $\mathbf{2 5}{ }^{\circ} \mathbf{C}$ to Peak Temperature | $3{ }^{\circ} \mathrm{C} /$ second(max) |  |
| Composition of solder paste | 8 minutes max. |  |
| Solder Paste Model |  | $96.5 \mathrm{Sn} / 3 \mathrm{Ag} / 0.5 \mathrm{Cu}$ |

The graphic shows temperature profile for component assembly process in reflow ovens


Soldering Iron condition: Soldering iron temperature $270^{\circ} \mathrm{C} \pm 10^{\circ} \mathrm{C}$.
Apply preheating at $120^{\circ} \mathrm{C}$ for $2-3$ minutes. Finish soldering for each terminal within 3 seconds, if soldering iron temperature over $270^{\circ} \mathrm{C} \pm 10^{\circ} \mathrm{C}$ or 3 seconds, it will make cause component surface peeling or damage.

## 6. Packaging

## 200 pcs per reel / inner carton <br> 5 reels per outer carton - 1,000 pcs



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